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U.S. DEPARTMENT OF COMMERCE

(Rev. 10/02) <b>Docket No.:</b> 70679-015	102788204	Patent and Trademark Office
To the Honorable Commissioner for Patents and Tradem		al documents or copy thereto:
1. Name of Conveying Party(ies):	2. Name and address of rece	
Seung-Ho PYI		ONDUCTOR INC.
	Address: San 136-1, Ami-	
Additional name(s) of conveying party(ies) attached?  Yes	,	-11, Bubai-cub,
3. Nature of Conveyance:		0 = 0.00 Paradia str
Assignment Merger	Kyoungki-do, 4	67-860 Republic of Korea
Security Agreement Change of Name		n 62
Other	,	8/8
Execution Date: June 2, 2004		10
Execution Date. Julie 2, 2004	Additional name(s) & addres	er(as) attached? \( \text{Vas} \) \( \text{No} \)
4. Application number(s) or patent number(s):	Additional name(s) & address	ss(es) attached?  Yes No
If the document is being filed together with a new application	on the execution date of the application	n is: June 2, 2004
A. Patent Application No(s).	B. Patent No(s).	n is: June 2, 2004
	B. Patent No(s).	
10/879757		
A 11:4: 1	 	
Additional numb		
5. Name and address of party to whom correspondence	6. Total number of application	ons and patents involved:
concerning document should be mailed:  Name: MCDERMOTT WILL & EMERY LLP		
	7. Total fee (37 CFR 3.41)	\$40.00
Internal Address:	Enclosed	
<b>G</b>	Authorized to be char	ged to deposit account
Street Address: 600 13th Street, N.W.	8. Deposit account number:	
	500417	
City: Washington State: D. C. Zip: 2000:	5-3096	
DO MO		
	T USE THIS SPACE	
9. Statement and signature.		
To the best of my knowledge and belief, the foregoing	information is true and correct and ar	ny attached copy is a true copy
of the original document.	0 10 4 .01	6
0.1	No 10 15 1, 50 10	O
Stephen A. Becker, 26,527	M, / W/ ) 600 ,	June 30, 2004
Name and Registration No. of Person Signing	Signature	Date
	Total number of pages including	cover sheet: 2
OMB No. 0651-0027 (exp. 6/30/2005)		

01 FC:8021 40.00 DA

Docket No.:			
ASSIGNMENT			
In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,			
PYI, Seung-Ho			
who has made a certain new and useful invention, hereby sells, assigns and transfers unto			
Hynix Semiconductor Inc.			
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled			
SEMICONDUCTOR DEVICE AND METHOD FOR ISOLATING THE SAME			
(a) for which an application for United States Letters Patent was filed on, and identified by United States Serial No; or			
(b) for which an application for United States Letters Patent was executed on			
and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;			
AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.			
SIGNED on the date indicated aside my signature:			
INVENTOR DATE SIGNED			
Pyi, Seung-140  Name: PYI, Seung-Ho  Jun., 2, 2004			

RECORDED: 06/30/2004

(SAB)

PATENT REEL: 015542 FRAME: 0767